

MASSACHUSETTS INSTITUTE OF TECHNOLOGY  
Department of Electrical Engineering and Computer Science

6.012 MICROELECTRONIC DEVICES AND CIRCUITS

Problem Set No. 4

**Issued:** September 30, 2009

**Due:** Monday, October 5, 2009 by 5 pm

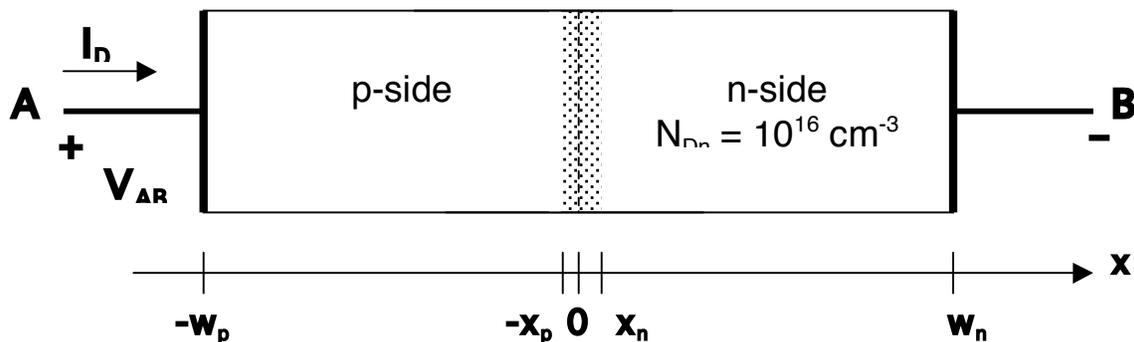
**Reading Assignments:**

- Lecture 7 (10/1/09) - Chap. 8 (8.1)  
Lecture 8 (10/6/09) - Chap. 7 (7.5, 7.6)  
Lecture 9 (10/8/09) - Chap. 9 (9.1, 9.2)

**Exam 1:** The first hour exam is scheduled for Wednesday night, October 7, from 7:30 to 9:30 pm. Please let me know as soon as possible (by e-mail) if you have a conflict so we can resolve it as painlessly as possible. The exam is closed book and will cover the material through 10/2/09 and Problem Set #4 (i.e. through p-n junction diodes and BJT basics). A formula sheet will be provided (see below); you can also bring one two-sided 8.5 x 11 crib sheet (and a magnifying glass if necessary). Old exams and solutions will be posted on Stellar soon.

**Formula Sheet:** A draft copy of the formula sheet has been posted on Stellar. Suggestions for additions, corrections, and/or deletions are welcome.

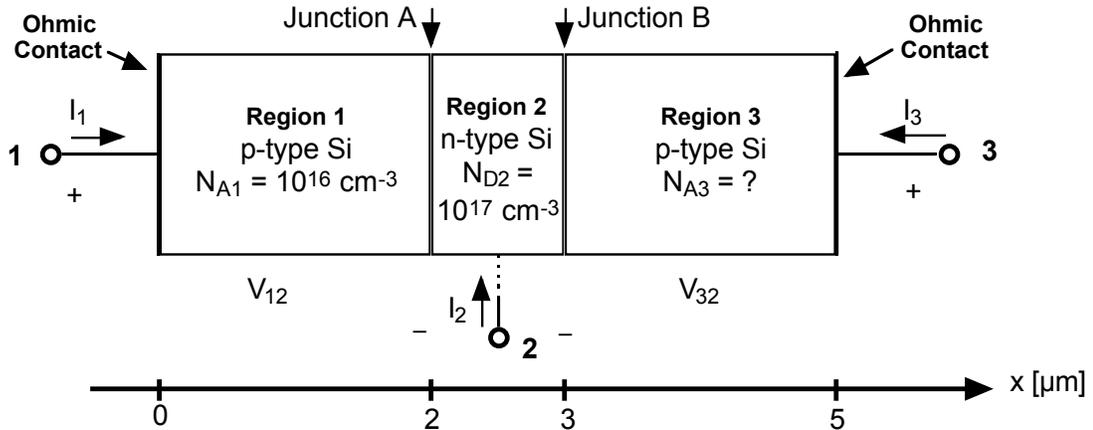
**Problem 1** - The p- and n-sides of the silicon p-n diode shown above are each  $2 \mu\text{m}$  wide; the depletion regions on either side of the junction are both much narrower than this and their widths can be neglected relative to  $2 \mu\text{m}$ ; also,  $L_{\text{min}} \gg 2 \mu\text{m}$ . The n-side has a net donor concentration,  $N_{\text{Dn}}$  of  $10^{16} \text{ cm}^{-3}$ . The hole and electron mobilities,  $\mu_h$  and  $\mu_e$ , are  $600 \text{ cm}^2/\text{V-s}$  and  $1600 \text{ cm}^2/\text{V-s}$ , respectively, throughout the device. (Ignore any dependence of the mobilities on doping level.) The cross-sectional area is  $10^{-4} \text{ cm}^2$ .



- a) When the bias voltage,  $V_{\text{AB}}$ , is 0.48 V, what are the following quantities?
- The total hole population at the contact on the right end of the device,  $w_n$
  - The total hole population at the edge of the depletion region on the n-side,  $x_n$ .

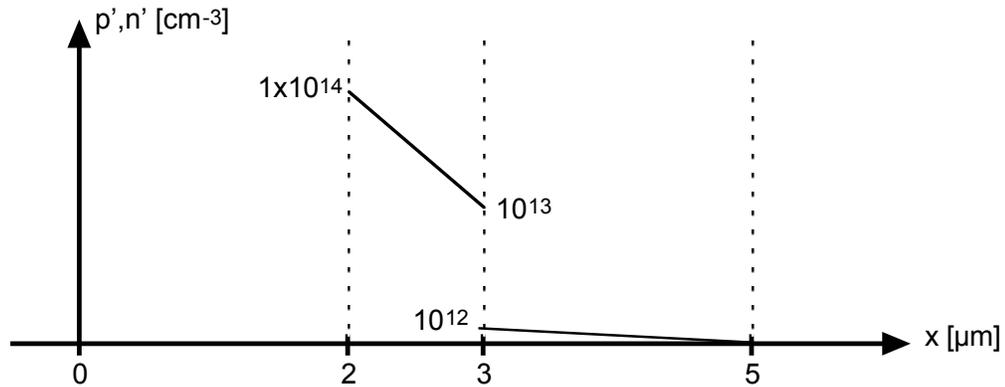
- iii) The excess hole charge stored in the quasi neutral region, QNR, on the n-side of the diode,  $q_{\text{QNR,n-side}}$ .
- iv) The net hole current density crossing the junction,  $J_h(0)$ .
- b) You are not told explicitly the doping level of the p-side of this diode,  $N_{A_p}$ , but you are told that the total minority carrier (electron) population at the edge of the depletion region on the p-side,  $n(-x_p)$  is one tenth that of the total minority carrier (hole) population at  $x_n$ ,  $p(x_n)$ , when the applied voltage,  $V_{AB}$ , is 0.48 V, that is  $p(x_n)/n(-x_p) = 10$ .
- What must the net acceptor concentration on the p-side,  $N_{A_p}$ , be?
  - What is the magnitude of the ratio of the excess electron charge,  $q_{\text{QNR,p-side}}$  stored on the p-side of this diode to the excess hole charge,  $q_{\text{QNR,n-side}}$  stored on the n-side at this bias?
  - What is the ratio of the net electron current density crossing the junction,  $J_e(0)$ , to the net hole current density,  $J_h(0)$ , at this bias point?
  - What is the total potential step going from the quasi-neutral region on the p-side to the quasi-neutral region on the n-side of the biased junction?

**Problem 2** - This question concerns the silicon sample illustrated below which has three uniformly doped regions: Regions 1 and 3 are p-type, and Region 2 is n-type. There are ohmic contacts on either end of the sample, and there is a contact to Region 2 off to the side (much as it is in a bipolar junction transistor). Throughout the sample the electron diffusion coefficient,  $D_e$ , is  $40 \text{ cm}^2/\text{s}$ , the hole diffusion coefficient,  $D_h$ , is  $15 \text{ cm}^2/\text{s}$ , and  $\tau_{\text{min}} \approx \infty$ . The cross-sectional area is  $10^{-4} \text{ cm}^2$ .



When Terminal 2 is grounded and bias voltages,  $V_{12}$  and  $V_{32}$ , are applied to this device, the excess minority carrier profiles shown at the top of the next page result in Regions 2 and 3. (You have to figure out what happens in Region 1 yourself.)

You can ignore the widths of the depletion regions for purposes of working this problem.



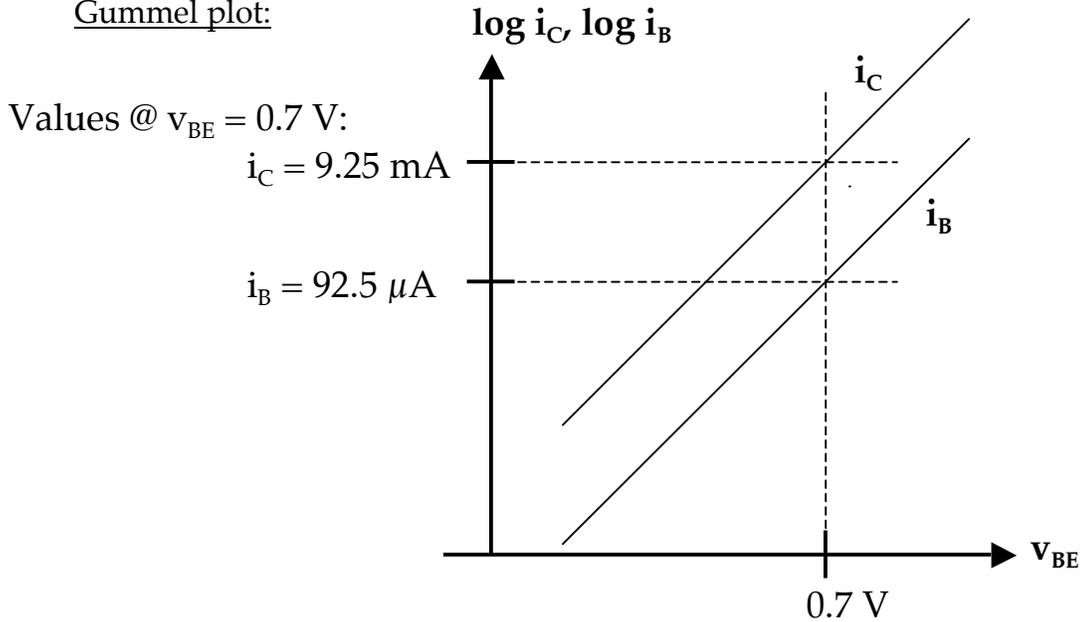
- (a) Looking at Junction B:
- What is  $J_{\text{Electron-B}}$ , the electron current density crossing Junction B? Recall that this is the minority carrier diffusion current density in Region 3.
  - What is  $J_{\text{Hole-B}}$ , the hole current density crossing Junction B?
  - What is the terminal current  $I_3$ ?
  - What is  $N_{A3}$ , the doping level in Region 3?
- (b) Looking at Junction A:
- What is  $n'(2^-)$ , the excess electron concentration at the edge of the quasi-neutral region on the p-side of this junction, i.e. just to the left of the edge of the depletion region at  $x = 2^-$ ?
  - What is  $V_{12}$ , the voltage bias on Junction A?
- (c) Looking now at the entire sample, removing the biases  $V_{12}$  and  $V_{32}$ , and thinking of the structure as a bipolar junction transistor:
- What is the best terminal to use as the emitter, and why?
  - For your choice of emitter above, what is the forward current gain,  $\beta_F$ , of this transistor?

**Problem 3** - You are given a silicon npn bipolar transistor with the following parameters:

$$\begin{aligned}
 W_E &= 0.25 \mu\text{m}, & W_B &= 0.5 \mu\text{m}, & W_C &= 1.0 \mu\text{m} \\
 \text{Active device cross-sectional areas: } & A_E = A_C = 10^{-4} \text{ cm}^2 \\
 D_h &= 10 \text{ cm}^2/\text{s}, & D_e &= 20 \text{ cm}^2/\text{s} \\
 \text{Minority carrier lifetime, } \tau_{\min} &= \infty \quad (\text{recombination only at contacts}) \\
 \text{Collector doping, } N_{DC} &= 5 \times 10^{16} \text{ cm}^{-3} \\
 V_A &= 100 \text{ V}
 \end{aligned}$$

A plot of  $\log i_C$  and  $\log i_B$  vs  $v_{BE}$  for this device is shown at the top of the next page. Such a plot is called a Gummel Plot, after the researcher who first realized that it was a useful tool for measuring  $\beta_F$  for BJTs and seeing if and how it varies with  $v_{BE}$ :

Gummel plot:



- What is the forward current gain,  $\beta_F$ , in this transistor?
- What is the base defect,  $\delta_B$ , in this transistor? (Hint: No calculation necessary.)
- Calculate the ratio,  $r$ , defined as  $r = (w_{E,eff} \cdot N_{DE}) / (w_{B,eff} \cdot N_{AB})$ .
- Calculate the net acceptor concentration in the base,  $N_{AB}$ . (Hint: Do not use your answer in Part c.)
- Calculate the net donor concentration in the emitter,  $N_{DE}$ .
- Plot the excess minority carrier profiles between  $x = -w_E$  and  $x = w_B + w_C$  for the bias condition  $V_{BE} = 0.7$  V,  $V_{BC} = -1$  V. Label the numerical values of the excess minority carrier concentrations at the edges of the depletion regions at  $x = 0$  and  $x = w_B$ , and at the contacts. (Note: Neglect the depletion region widths relative to the emitter, base, and collector widths.)
- Consider the total number of excess minority carriers in the base of this transistor,  $Q_{B,diff}$ , under each of the following two bias conditions,
 

Bias A:	$V_{BE} = 0.7$ V	$V_{BC} = -1$ V
Bias B:	$V_{BE} = 0.7$ V	$V_{BC} = 0.7$ V

What is the ratio of the  $Q_{B,diff}$ 's under the two bias conditions? (Suggestion: Try sketching  $n'(x)$  for  $0 < x < w_B$  for each of these biases.)

MIT OpenCourseWare  
<http://ocw.mit.edu>

6.012 Microelectronic Devices and Circuits  
Fall 2009

For information about citing these materials or our Terms of Use, visit: <http://ocw.mit.edu/terms>.